

20-3001 EPOXY POTTING AND ENCAPSULATING RESIN

DESCRIPTION

20-3001 is a low viscosity, unfilled epoxy potting and encapsulating system which forms a bubble free glass like finish when cured.

This is a 100% solids resin system that does not contain any solvents. Its convenient 1:1 mix ratio and lack of fillers make it an ideal material for meter mix and dispense equipment. 20-3001 has been formulated for ease in handling. Its low viscosity aids in filling voids and air pockets. In addition, there is no filler settling with this system.

The engineering staff at Epoxies, Etc... is at your service to answer questions about your particular requirements. Sample kits are available from stock.

TYPICAL SPECIFICATIONS

Mix ratio, by volume	1:1
Mix ratio, by weight	100:83
Mix viscosity, @ 25° C cps	1,000
Pot life, 100 gram mass, @ 25° C	20 minutes
Specific gravity, @ 25° C	1.12
Hardness, Shore D	55-60
Tensile strength, psi	5,700
Thermal conductivity, BTU in/ft ² /hr/f	3.0
Thermal expansion coefficient per °C	50x10 ⁻⁶
Operating temperature °C	-50 to +150
Dielectric strength, volts/mil	558
Dielectric constant, 60 HZ	4.7
Dissipation factor, 60 HZ	.034
Volume resistivity, ohm-cm	5.0x10 ¹⁵

AVAILABILITY

20-3001 is available in 50ml, 75ml, 200ml and 400 ml dual barrel syringes. It is also available in quarts, gallons and 5 gallon pails.

INSTRUCTIONS FOR USE

By volume, thoroughly mix equal parts resin and catalyst.
By weight, thoroughly mix 100 parts 20-3001 resin to 83 parts catalyst.
Pour and cure 12-16 hours at room temperature.



IMPORTANT

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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